

Chemical Compositions															
MATERIAL DESIGNATION EN1652 or Alloy		NEAREST FIT		TYPICAL CHEMICAL COMPOSITION %											
Symbol/ Name	Number	UNS	BS 2870	Cu	Be	Co	Fe	Mn	Ni	P	Pb	Sn	Zn	Others	Impurities
HIGH CONDUCTIVITY COPPERS															
Cu-ETP	CW004A	C11000	C101	99.9 min	-	-	-	-	-	-	0.005	-	-	Bi: 0.0005 O: 0.04	-
Cu-ETP1	CW003A	C11040	-	Available by Request											
Cu-HCP	CW021A	C10300	C102	99.95 min	-	-	-	-	-	0.002 - 0.007	-	-	-	-	-
Cu-OF	CW008A	C10200	C103	99.95 min	-	-	-	-	-	-	0.005	-	-	Bi: 0.0005	0.03
Cu-DHP	CW024A	C12200	C106	99.9 min	-	-	-	-	-	0.005 - 0.013	0.005	-	-	-	0.03

Mechanical Properties								
MATERIAL DESIGNATION EN1652 or Alloy		NEAREST FIT		Material Condition (R Value)	Proof Strength 0.2% Min (N/mm2)	Tensile Strength (N/mm2)	Elong. % Min. (50mm Gauge Length)	Hardness Max (VPN)
Symbol/ Name	Number	UNS	BS 2870					
HIGH CONDUCTIVITY COPPERS								
Cu-ETP	CW004A	C11000	C101	R220	140 Max	220-260	33	40-65
				R240	180 Min	240-360	8	65-95
				R290	250 Max	290-360	4	90-110
				R360	320 Min	360 Min	2	110 Min
Cu-HCP	CW021A	C10300	C102	R220	140 Max	220-260	33	40-65
				R240	180 Min	240-360	8	65-95
				R290	250 Max	290-360	4	90-110
				R360	320 Min	360 Min	2	110 Min
Cu-OF	CW008A	C26000	C103	R220	140 Max	220-260	33	40-65
				R240	180 Min	240-360	8	65-95
				R290	250 Max	290-360	4	90-110
				R360	320 Min	360 Min	2	110 Min
Cu-DHP	CW024A	C12200	C106	R220	140 Max	220-260	33	40-65
				R240	180 Min	240-360	8	65-95
				R290	250 Max	290-360	4	90-110
				R360	320 Min	360 Min	2	110 Min

Features and Applications					
MATERIAL DESIGNATION BSEN1652 (Strip) BSEN12166 (Wire)		NEAREST FIT		Key Features	Key Markets
Symbol/ Name	Number	UNS	BS 2870 (Strip) BS 2873 (Wire)		
HIGH CONDUCTIVITY COPPERS					
Cu-ETP	CW004A	C11000	C101	Cu-ETP has no susceptibility to hydrogen embrittlement as well as a high electrical conductivity of 101% IACS. This is due to a high purity and an absence of deoxidisers.	Architectural, Chemical Engineering, Culinary, Electrical
Cu-ETP1	CW003A	C11040	-	Available by Request	
Cu-HCP	CW021A	C10300	C102	Cu-HCP is a de-oxidised, oxygen-free Copper with a low residual phosphorus content. Offers excellent formability and weldability, as well as good soldering and brazability.	Electrical, Manufacturing
Cu-OF	CW008A	C10200	C103	Cu-OF is a High purity Copper Oxygen Free (maximum of 10ppm) alloy, offering 100% IACS. It is immune from hydrogen embrittlement and offers similar formability to Cu-ETP.	Electronics, Telecommunications
Cu-DHP	CW024A	C12200	C106	Cu-DHP is a de-oxidised, non-arsenical, oxygen-free 99.9% pure Copper, with limited residual phosphorus content. It offers excellent formability and weldability, as well as good corrosion resistance. This makes it ideal for applications where electrical conductivity is only of secondary importance.	Architectural, Electrical, Plumbing